



# eUICC SIM Datasheet

V1.1 | JULY 2020

# Triple-cut form factor

2FF, 3FF, 4FF

## Product Overview

A secure IoT SIM card for a global cell network built for M2M data with easy activation, transparent pricing, and developer-friendly tools.

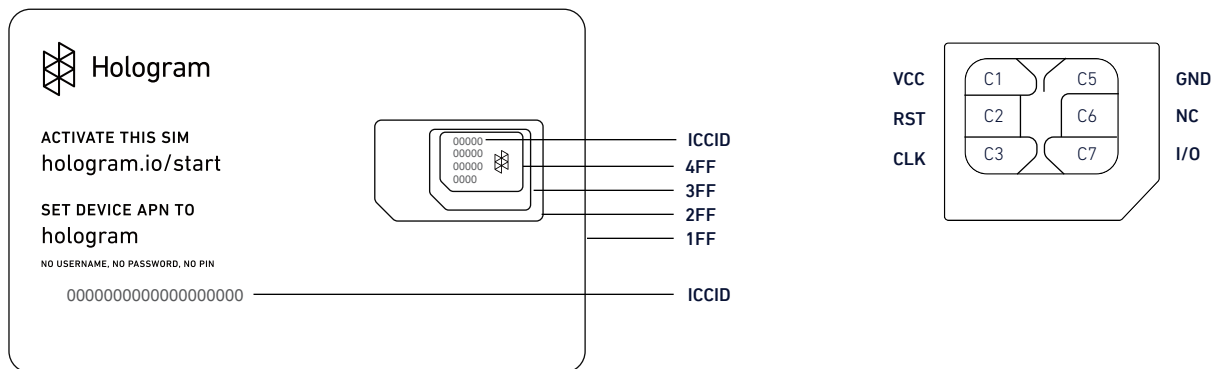
## Orderable part numbers

|                   |                   |
|-------------------|-------------------|
| SIM-E-TRI-GL      | SIM-E-TRI-LS      |
| SIM-E-TRI-GL-10   | SIM-E-TRI-LS-10   |
| SIM-E-TRI-GL-100  | SIM-E-TRI-LS-100  |
| SIM-E-TRI-GL-1000 | SIM-E-TRI-LS-1000 |

## Network Availability

Works globally with Hologram's 2G through LTE network where coverage is available.  
More information: <https://www.hologram.io/pricing/coverage>

## Mechanical specifications



### Size

|     |           |                        |
|-----|-----------|------------------------|
| 1FF | Full-size | 85.5 x 53.98 x 0.76 mm |
| 2FF | Mini-SIM  | 25 x 15 x 0.76 mm      |
| 3FF | Micro-SIM | 15 x 12 x 0.76 mm      |
| 4FF | Mini-SIM  | 12.3 x 8.8 x 0.76 mm   |

### Pin Definitions

|    |     |               |
|----|-----|---------------|
| C1 | VCC | Input Voltage |
| C2 | RST | Reset         |
| C3 | CLK | Clock         |
| C5 | GND | Ground        |
| C6 | NC  | No Connect    |
| C7 | I/O | Input/Output  |

## Hardware Specifications

| Environmental | Standard Grade         | Industrial Grade       |
|---------------|------------------------|------------------------|
| Temperature   | -25–85°C               | -40–105°C              |
| Lifespan      | 25 years @ 25°C        | 15 years @ 85°C        |
| Lifespan      | 100K read/write cycles | 500K read/write cycles |

| Electrical        | Standard Grade | Industrial Grade |
|-------------------|----------------|------------------|
| Operating Voltage | 1.62V–5.5V     | 1.62V–5.5V       |

### AC electrical parameters standards

ETSI 3GPP TS 102 221(UICC Terminal Interface Physical & Logical Characteristics)

ETSI TS 102 671 v9.1.0(M2M Physical and Logical Characteristics)

ISO 7816-3 standard for (Cards with Contacts - Electrical interface and transmission protocols)

## Compliance

|                         |  |  |
|-------------------------|--|--|
| Chip                    |  Common Criteria                     | EAL: PP-0084/35  |
| OS                      |  GSMA                               | SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; SGP.02 v3.2 ; SGP.05 eUICC PP-0089 |
|                         |  simalliance                        | eUICC Profile Package v2.1   |
|                         |  GLOBALPLATFORM®                    | Product Qualification  |
| Production              |  GSMA Security Accreditation Scheme | SAS-UP eUICC : EUM   |
| Remote SIM provisioning |  GSMA                               | SGP.01 RSP v1.1 ; SGP.11 RSP v3.1 & 3.2; SGP.14 eUICC PKI v1.1 ; SAS-SM    |

## RoHS and REACH Compliance

Hologram, Inc. hereby declares that the aforementioned Hologram products, placed on the European Community market by the Company and its subsidiaries is compliant with Directive 2011/65/EU on the Restriction of Certain Hazardous Substances in Electrical and Electronic Equipment.

More information: <https://www.samsung.com/semiconductor/about-us/global-compliance/>

# Embedded form factor

MFF2, QFN8

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## Orderable part numbers

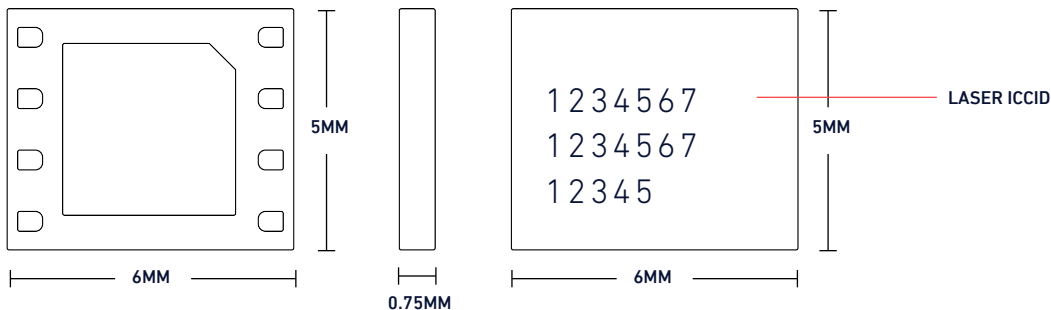
|                    |                    |
|--------------------|--------------------|
| SIM-E-MFF2-GL      | SIM-E-MFF2-LS      |
| SIM-E-MFF2-GL-10   | SIM-E-MFF2-LS-10   |
| SIM-E-MFF2-GL-100  | SIM-E-MFF2-LS-100  |
| SIM-E-MFF2-GL-1000 | SIM-E-MFF2-LS-1000 |

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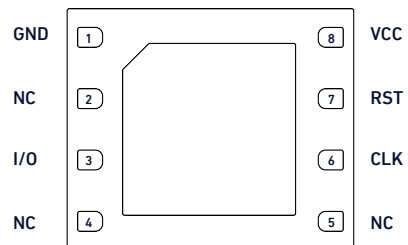
### Bottom View



### Pin Definitions

|   |     |               |
|---|-----|---------------|
| 1 | GND | Ground        |
| 2 | NC  | No Connect    |
| 3 | I/O | Input/Output  |
| 4 | NC  | No Connect    |
| 5 | NC  | No Connect    |
| 6 | CLK | Clock         |
| 7 | RST | Reset         |
| 8 | VCC | Input Voltage |

### Top View



### Size

6 x 5 x 0.75mm

## Hardware Specifications

| Environmental | Standard Grade         | Industrial Grade       |
|---------------|------------------------|------------------------|
| Temperature   | -25–85°C               | -40–105°C              |
| Lifespan      | 25 years @ 25°C        | 15 years @ 85°C        |
| Lifespan      | 100K read/write cycles | 500K read/write cycles |

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|-------------------|----------------|------------------|
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